Form 1449 (Modified)

Information Disclosure
Statement By Applicant

(Use Several Sheets if Necessary)

Atty. Docket No.
NVIDP235/P000846
10/633,021
Applicant:
Singh et al.
Filing Date:
Group Art Unit:
Unassigned

U.S. Patent Documents

U.S. Patent Documents							
Examiner				-		Sub-	Filing
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Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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7/31/2003

Group Art Unit:

Unassigned 261

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	AA BB CC DD EE FF GG HH II JJ KK LL MM NN OO PP QQ RR	Y 6,448,641 Z 6,486,051 AA 6,489,688 BB 6,087,732 CC 5,027,188 DD 6,329,712 EE 5,986,343 FF 6,016,000 GG HH II JJ KK LL MM NN OO PP QQ RR	No. Patent No. Date Y 6,448,641 09/10/2002 Z 6,486,051 11/26/2002 AA 6,489,688 12/03/2002 BB 6,087,732 07/11/2000 CC 5,027,188 06/25/1991 DD 6,329,712 12/11/2001 EE 5,986,343 11/16/1999 FF 6,016,000 01/18/2000 GG HH II JJ KK LL MM NN OO PP QQ RR	Y 6,448,641 09/10/2002 Ker et al. Z 6,486,051 11/26/2002 Sabin et al. AA 6,489,688 12/03/2002 Baumann et al. BB 6,087,732 07/11/2000 Chittipeddi et al. CC 5,027,188 06/25/1991 Owada et al. DD 6,329,712 12/11/2001 Akram et al. EE 5,986,343 11/16/1999 Chittipeddi et al. FF 6,016,000 01/18/2000 Moslehi GG HH HI II JJ KK II II MM II StGG Tteles (s) NN OO PP QQ RR	No. Patent No. Date Patentee Class Y 6,448,641 09/10/2002 Ker et al. 257 Z 6,486,051 11/26/2002 Sabin et al. 438 AA 6,489,688 12/03/2002 Baumann et al. 257 BB 6,087,732 07/11/2000 Chittipeddi et al. 257 CC 5,027,188 06/25/1991 Owada et al. 357 DD 6,329,712 12/11/2001 Akram et al. 257 EE 5,986,343 11/16/1999 Chittipeddi et al. 257 FF 6,016,000 01/18/2000 Moslehi 257 GG HH II II II II JJ KK II II	No. Patent No. Date Patentee Class Class Y 6,448,641 09/10/2002 Ker et al. 257 700 Z 6,486,051 11/26/2002 Sabin et al. 438 612 AA 6,489,688 12/03/2002 Baumann et al. 257 786 BB 6,087,732 07/11/2000 Chittipeddi et al. 257 786 CC 5,027,188 06/25/1991 Owada et al. 357 68 DD 6,329,712 12/11/2001 Akram et al. 257 700 EE 5,986,343 11/16/1999 Chittipeddi et al. 257 758 FF 6,016,000 01/18/2000 Moslehi 257 522 GG HH

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Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication				
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Examiner	·	HUNG VU Date Considered W/05/04				

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.